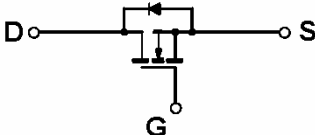


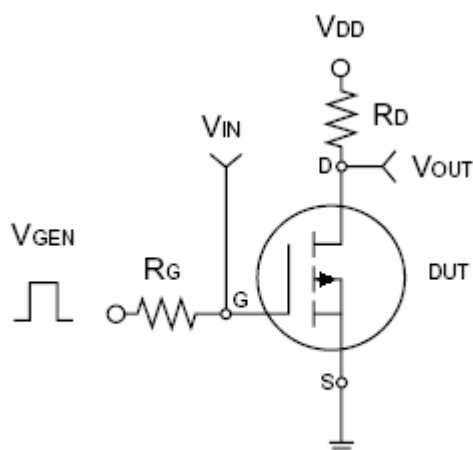
20V N-Channel Enhancement Mode MOSFET

SOT-23  Pin assignment: 1. Gate 2. Source 3. Drain	V_{DS} = 20V R_{DS (on)}, V_{GS} @ 4.5V, I_{DS} @ 3.6A = 65mΩ R_{DS (on)}, V_{GS} @ 2.5V, I_{DS} @ 3.1A = 95mΩ																																																
Features ✧ Advanced trench process technology ✧ High density cell design for ultra low on-resistance	✧ Excellent thermal and electrical capabilities ✧ Compact and low profile SOT-23 package																																																
Block Diagram 	Ordering Information <table><tr><th>Part No.</th><th>Packing</th><th>Package</th></tr><tr><td>RTM2302CX</td><td>Tape & Reel</td><td>SOT-23</td></tr></table>	Part No.	Packing	Package	RTM2302CX	Tape & Reel	SOT-23																																										
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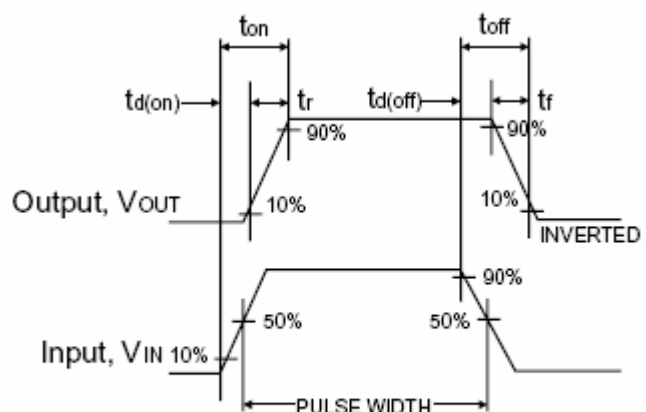
Note: Surface mounted on FR4 board t<=5sec.

Electrical Characteristics						
Rate I _D = 2.4A, (Ta = 25 °C unless otherwise noted)						
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250uA	BV _{DSS}	20	--	--	V
Drain-Source On-State Resistance	V _{GS} = 4.5V, I _D = 3.6A	R _{DS(ON)}	--	50	65	mΩ
Drain-Source On-State Resistance	V _{GS} = 2.5V, I _D = 3.1A	R _{DS(ON)}	--	75	95	
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250uA	V _{GS(TH)}	0.45	--	--	V
Zero Gate Voltage Drain Current	V _{DS} = 20V, V _{GS} = 0V	I _{DSS}	--	--	1.0	uA
Gate Body Leakage	V _{GS} = ± 8V, V _{DS} = 0V	I _{GSS}	--	--	± 100	nA
On-State Drain Current	V _{DS} ≥ 5V, V _{GS} = 4.5V	I _{D(ON)}	6	--	--	A
Forward Transconductance	V _{DS} = 5V, I _D = 3.6A	g _{fs}	--	10	--	S
Dynamic						
Total Gate Charge	V _{DS} = 10V, I _D = 3.6A, V _{GS} = 4.5V	Q _g	--	5.2	10	nC
Gate-Source Charge		Q _{gs}	--	0.65	--	
Gate-Drain Charge		Q _{gd}	--	1.5	--	
Turn-On Delay Time	V _{DD} = 10V, R _L = 10Ω, I _D = 1A, V _{GEN} = 4.5V, R _G = 6Ω	t _{d(on)}	--	7	15	nS
Turn-On Rise Time		t _r	--	55	80	
Turn-Off Delay Time		t _{d(off)}	--	16	60	
Turn-Off Fall Time		t _f	--	10	25	
Input Capacitance	V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz	C _{iss}	--	450	--	pF
Output Capacitance		C _{oss}	--	70	--	
Reverse Transfer Capacitance		C _{rss}	--	43	--	
Source-Drain Diode						
Max. Diode Forward Current		I _S	--	--	1.6	A
Diode Forward Voltage	I _S = 1.0A, V _{GS} = 0V	V _{SD}	--	0.75	1.2	V

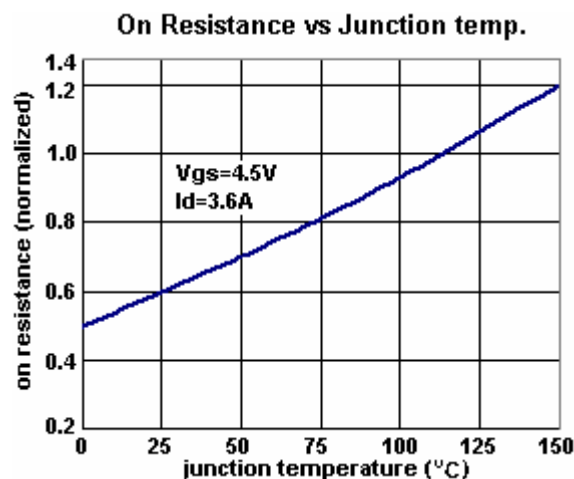
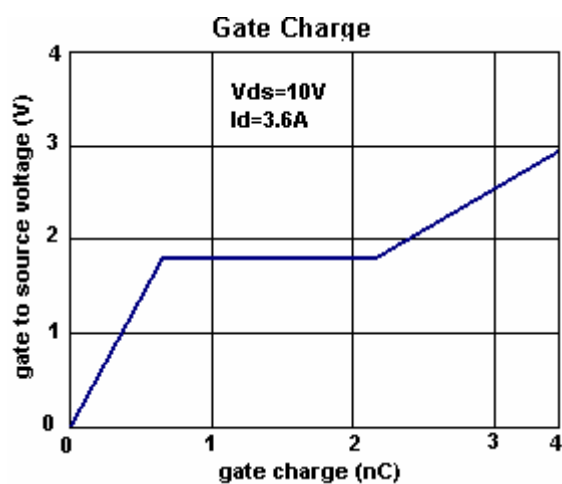
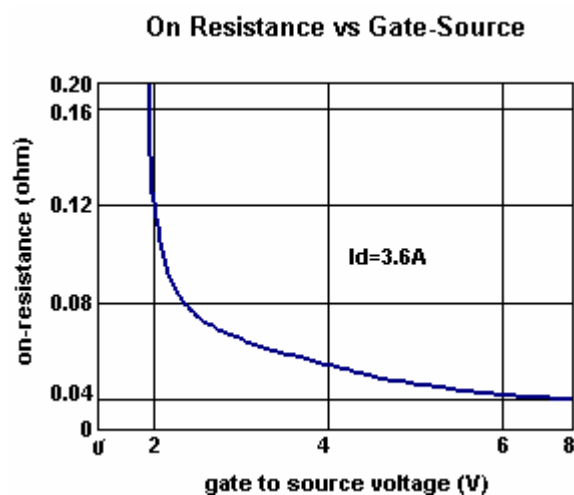
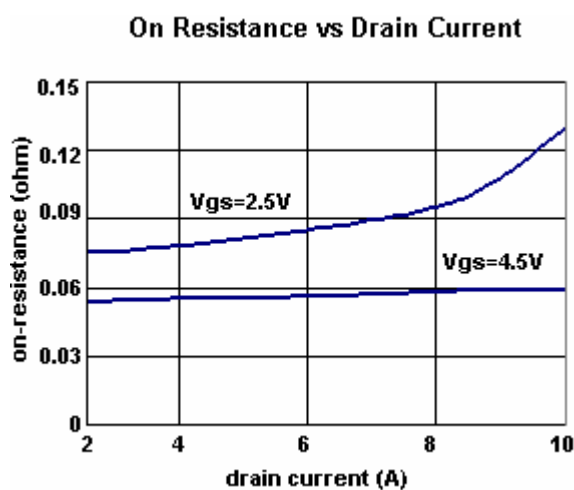
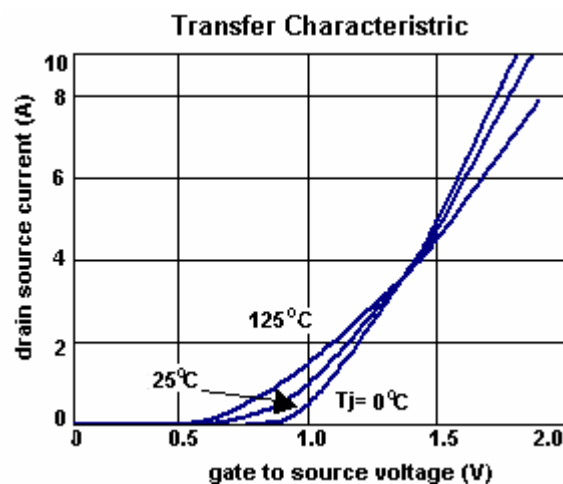
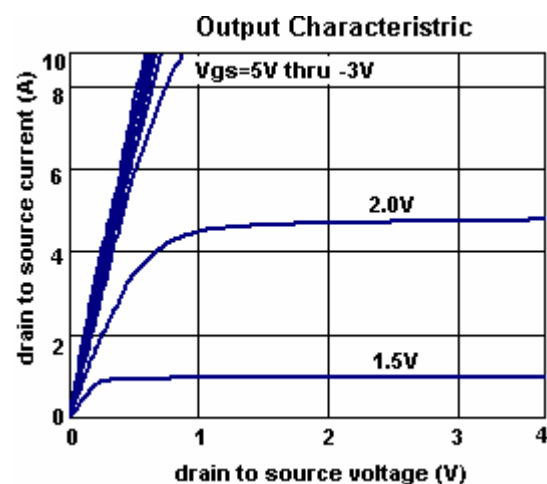
Note : pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

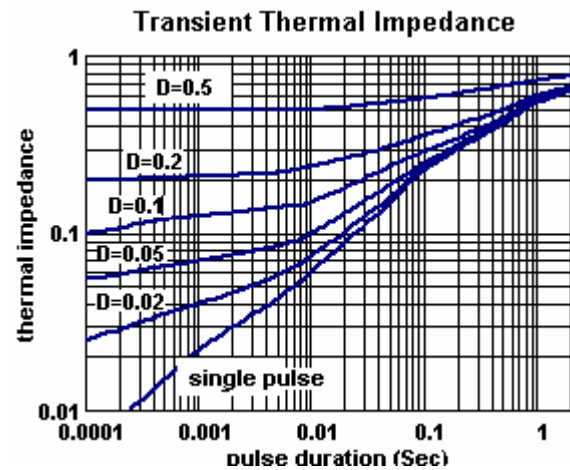
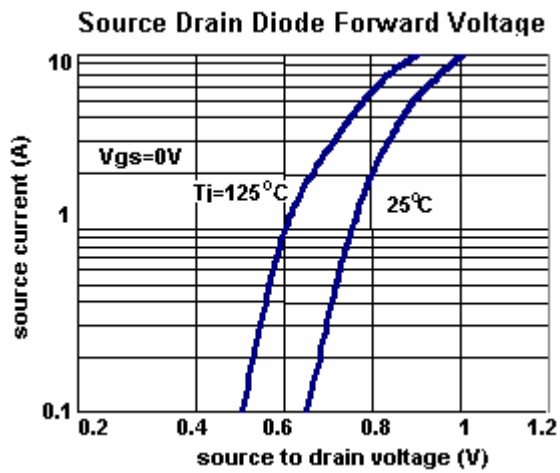


Switching Test Circuit

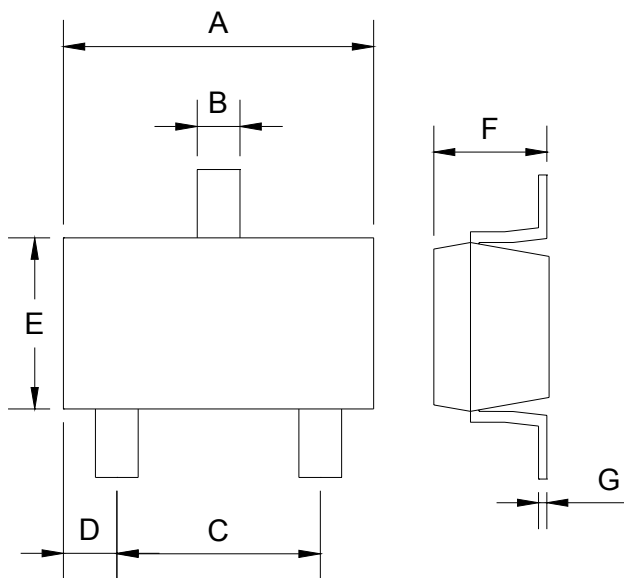


Switchin Waveforms

Typical Characteristics Curve ($T_a = 25^\circ\text{C}$ unless otherwise noted)


Typical Characteristics Curve ($T_a = 25^\circ\text{C}$ unless otherwise noted)


SOT-23 Mechanical Drawing



DIM	SOT-23 DIMENSION			
	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.88	2.91	0.113	0.115
B	0.39	0.42	0.015	0.017
C	1.78	2.03	0.070	0.080
D	0.51	0.61	0.020	0.024
E	1.59	1.66	0.063	0.065
F	1.04	1.08	0.041	0.043
G	0.07	0.09	0.003	0.004